

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16 D-32758 Detmold

Germany

Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com











The integrated rail bus for the modular electronics housing system

When supplying, connecting or distributing within modular applications, the rail bus can replace the tedious individual wiring process with a flexible and uninterrupted system-wide solution.

The system bus is securely integrated within the 35-mm standard mounting rail. The SMD-bus contact block can be reflow-soldered so that it can be completely automatically processed during the component assembly. The resistant, gold-plated contact surfaces ensure a permanent and reliable contact for all housing widths.

- **Unlimited scalability** The integrated connection solution covers all system widths: from the 6-mm slice to the 67-mm large-area housing.
- Easy to service during installation It's easy to replace a module, even in existing modules groups – without any influence on the neighbouring modules.
- **Universal integration** The uninterrupted system bus is securely integrated within the 35-mm standard mounting rail.
- Maximum availability Five fully-galvanized and partially gold-plated twin-arched contacts are used to establish a permanent contact to the rail bus. THR solder flanges ensure that the connection to the circuit board is stable.

General ordering data

| Туре | SR-SMD 4.50/05/90LF 1.5AU BK BX |
|--------------|--|
| Order No. | <u>1155890000</u> |
| Version | PCB plug-in connector, Bus-contact block for CH20M12-67, Solder flange, THT/THR solder connection, No. of poles: 5, 180°, Solder pin length (I): 1.5 mm, Gold-plated, black |
| GTIN (EAN) | 4032248942527 |
| Qty. | 78 pc(s). |
| Product data | UL: |
| Packaging | Вох |



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Technical data

Dimensions and weights

| Length | 24 mm | Length (inches) | 0.945 inch |
|------------|---------|-----------------|------------|
| Width | 16.3 mm | Width (inches) | 0.642 inch |
| Height | 5.9 mm | Height (inches) | 0.232 inch |
| Net weight | 3.05 g | | |

System specifications

| Product family | OMNIMATE Housing - | Type of connection | |
|-----------------------------|--------------------|-----------------------|------------------|
| • | series CH20M | | Board connection |
| Mounting onto the PCB | THT/THR solder | Pitch in mm (P) | |
| | connection | | 5 mm |
| Pitch in inches (P) | 0.197 inch | Outgoing elbow | 180° |
| No. of poles | 5 | Solder pin length (I) | 1.5 mm |
| Solder pin length tolerance | +0.1 / -0.3 mm | L1 in mm | 20 mm |
| L1 in inches | 0.787 inch | Pin series quantity | 1 |
| Plugging cycles | 25 | - | |

Material data

| Insulating material | LCP | Colour code | black |
|---------------------------------------|----------|---------------------------------------|---------------------|
| Colour chart (similar) | RAL 9011 | Insulating material group | IIIa |
| СТІ | ≥ 175 | Insulation strength | ≥ 10 ⁸ Ω |
| Moisture Level (MSL) | 1 | Contact surface | Gold-plated |
| Storage temperature, min. | -25 °C | Storage temperature, max. | 55 °C |
| Max. relative humidity during storage | 80 % | Operating temperature, min. | -50 °C |
| Operating temperature, max. | 100 °C | Temperature range, installation, min. | -30 °C |
| Temperature range, installation, max. | 100 °C | | |

Rated data acc. to IEC

| tested acc. to standard | IEC 60664-1, IEC 61984 | |
|-------------------------|------------------------|--|

Classifications

| ETIM 4.0 | EC002637 | ETIM 5.0 | EC002637 |
|------------|-------------|------------|-------------|
| ETIM 6.0 | EC001031 | eClass 6.2 | 27-26-07-04 |
| eClass 7.1 | 27-44-04-02 | eClass 8.1 | 27-44-04-02 |
| eClass 9.0 | 27-18-27-90 | eClass 9.1 | 27-18-27-90 |

Notes

| Notes | |
|----------------|--|
| IPC conformity | Conformity: The products are developed, manufactured and delivered according international recognized |
| | standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties |
| | in accordance with IPC-A-610 "Class 2" Further claims on the products can be evaluated on request |

Approvals

Approvals

Caracteristics

Conform

Conform



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Technical data

Downloads

| Brochure/Catalogue | FL ANALO.SIGN.CONV. EN |
|--------------------|-------------------------|
| | MB DEVICE MANUF. EN |
| | CAT 2 PORTFOLIOGUIDE EN |
| | FL MACHINE SAFETY EN |
| | FL 72H SAMPLE SER EN |
| | PO OMNIMATE EN |
| Engineering Data | STEP |



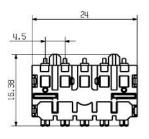
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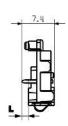
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Drawings

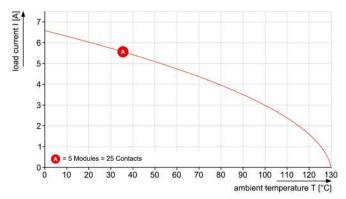












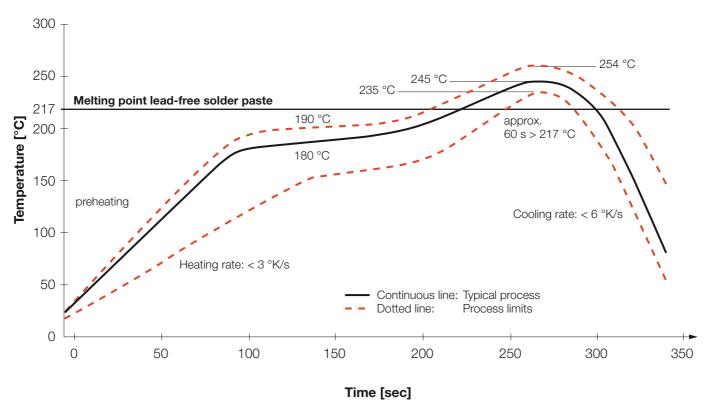


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.



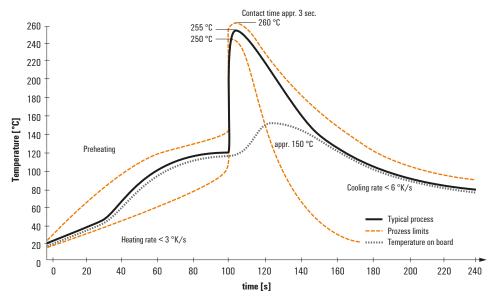
Recommended wave solderding profiles

Weidmüller Interface GmbH & Co. KG

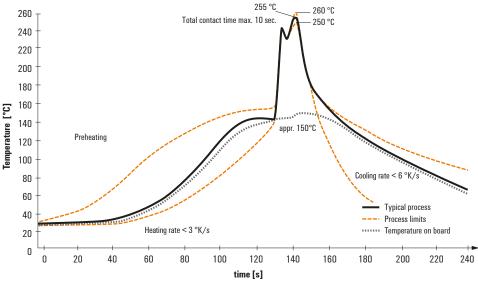
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

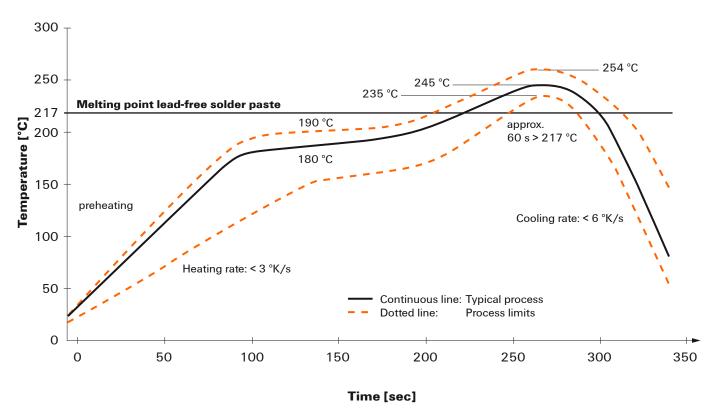


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